



SLOVENSKI STANDARD
oSIST prEN IEC 62769-4:2022
01-maj-2022

Integracija procesne naprave (FDI) - 4. del: Paketi FDI

Field Device Integration (FDI) - Part 4: FDI Packages

Feldgeräteintegration (FDI) - Teil 4: FDI-Packages

Intégration des appareils de terrain (FDI) - Partie 4: Paquetages FDI

Ta slovenski standard je istoveten z: **prEN IEC 62769-4:2022**

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ICS:

25.040.40 Merjenje in krmiljenje industrijskih postopkov
35.240.50 Uporabniške rešitve IT v industriji

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65E/857/CDV

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SECRETARIAT: United States of America	SECRETARY: Mr Donald (Bob) Lattimer
OF INTEREST TO THE FOLLOWING COMMITTEES: SC 65B, SC 65C	PROPOSED HORIZONTAL STANDARD: <input type="checkbox"/> Other TC/SCs are requested to indicate their interest, if any, in this CDV to the secretary.
FUNCTIONS CONCERNED: <input type="checkbox"/> EMC <input type="checkbox"/> ENVIRONMENT <input type="checkbox"/> QUALITY ASSURANCE <input type="checkbox"/> SAFETY	
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<p>Attention IEC-CENELEC parallel voting</p> <p>The attention of IEC National Committees, members of CENELEC, is drawn to the fact that this Committee Draft for Vote (CDV) is submitted for parallel voting.</p> <p>The CENELEC members are invited to vote through the CENELEC online voting system.</p>	

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TITLE:

Field Device Integration (FDI) - Part 4: FDI Packages

PROPOSED STABILITY DATE: 2025

NOTE FROM TC/SC OFFICERS:

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

FIELD DEVICE INTEGRATION (FDI) –

Part 4: FDI Packages

FOREWORD

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IEC 62769-4 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2021. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) added DocumentClass to Package Schema, Description of Feature Table and Documentation Catalog, individual schemas for Feature Table and Package Documentation Catalog, schema for UnitConversion, interactive download to device, and Feature Unit Conversion;
- b) moved DocumentClass to Package Documentation Catalog Schema;
- c) updated Description of Feature Table updated XML schema for Feature Table.

308 The text of this International Standard is based on the following documents:

Draft	Report on voting
XX/XX/FDIS	XX/XX/RVD

309

310 Full information on the voting for its approval can be found in the report on voting indicated in the above
311 table.

312 The language used for the development of this International Standard is English.

313 This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance
314 with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at
315 www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in
316 greater detail at www.iec.ch/standardsdev/publications.

317 The committee has decided that the contents of this document will remain unchanged until the stability
318 date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific
319 document. At this date, the document will be

- 320 • reconfirmed,
- 321 • withdrawn,
- 322 • replaced by a revised edition, or
- 323 • amended.

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FIELD DEVICE INTEGRATION (FDI) – Part 4: FDI Packages

1 Scope

This part of IEC 62769 specifies the FDI Packages. The overall FDI architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in this figure.

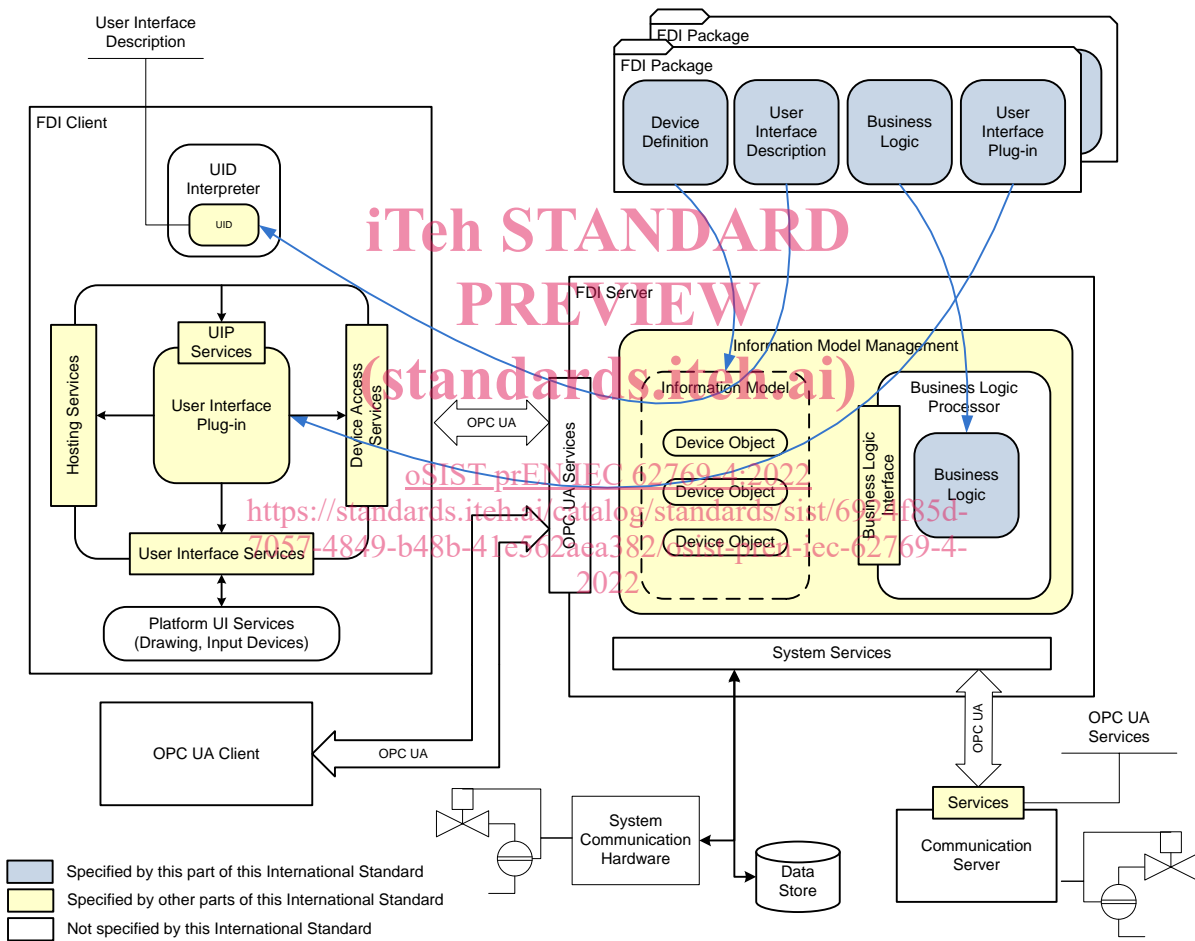


Figure 1 – FDI architecture diagram

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

342 IEC 61804-3, Function blocks (FB) for process control and Electronic Device Description Language
343 (EDDL) – Part 3: EDDL syntax and semantics

344 IEC 61804-5:2020, Function blocks (FB) for process control and Electronic Device Description Language
345 (EDDL) – Part 5: EDDL Builtin library

346 FCG TS10099, *Field Device Integration (FDI) – Technology Management*

347 IEC 62769-1, Field Device Integration (FDI) – Part 1: Overview

348 IEC 62769-2, Field Device Integration (FDI) – Part 2: FDI Client

349 IEC 62769-5, Field Device Integration (FDI) – Part 5: FDI Information Model

350 IEC 62769-6, Field Device Integration (FDI) – Part 6: FDI Technology Mapping

351 IEC 62769-7, Field Device Integration (FDI) – Part 7: FDI Communication Devices

352 ISO/IEC 11578, Information technology – Open Systems Interconnection – Remote Procedure Call (RPC)

353 ISO/IEC 29500-2:2011, Information technology – Document description and processing languages –
354 Office Open XML File Formats – Part 2: Open Packaging Conventions

355 ISO 639-1, Codes for the representation of names of languages – Part 1: Alpha-2 code

356 ISO 32000-1, Document management – Portable document format – Part 1: PDF 1.7

357 Dublin Core Metadata Initiative: DCMI Metadata Terms, 2020

358 **3 Terms, definitions, abbreviated terms and acronyms**

359 **3.1 Terms and definitions**

360 For the purposes of this document, the terms and definitions given in IEC 62769-1, ISO/IEC 29500-2, and
361 the following apply.

362 **3.1.1**

363 **attachment**

364 device and protocol specific support files that are not directly used to integrate the Device into the system

365 **3.1.2**

366 **FDI Communication Package**

367 FDI Package that provides information to integrate an FDI Communication Server to an FDI Server

368 Note 1 to entry: This note applies to the French language only.

369

370 **3.1.3**

371 **FDI Device Package**

372 FDI Package that provides one or more device types to an FDI Server

373 Note 1 to entry: This note applies to the French language only.

374 **3.1.4**

375 **FDI Package Model**

376 description of the structure and elements of an FDI Package

377 Note 1 to entry: This note applies to the French language only.